

AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): Shibaek Nam, et al.

Docket No.
24317/81501Serial No.
10/038,714Filing Date
01/02/2002O
JC59
AUG 21 2003
REMARKS OFFICEExaminer
Pershelle L. GreeneGroup Art Unit
2826

Invention: Semiconductor Device Having Multi-Chip Package Structure

RECEIVED
SEP - 3 2003
TECHNOLOGY CENTER 2800

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

| | CLAIMS REMAINING AFTER AMENDMENT | HIGHEST # PREV. PAID FOR | NUMBER EXTRA CLAIMS PRESENT | RATE | ADDITIONAL FEE |
|--|-------------------------------------|-----------------------------|--------------------------------|-----------|-------------------|
| TOTAL CLAIMS | 14 - | 49 = | 0 | x \$18.00 | \$0.00 |
| INDEP. CLAIMS | 2 - | 3 = | 0 | x \$84.00 | \$0.00 |
| Multiple Dependent Claims (check if applicable) <input type="checkbox"/> | | | | | \$0.00 |
| TOTAL ADDITIONAL FEE FOR THIS AMENDMENT | | | | | \$0.00 |

No additional fee is required for amendment.

Please charge Deposit Account No. in the amount of
A duplicate copy of this sheet is enclosed.

A check in the amount of to cover the filing fee is enclosed.

The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-1597
A duplicate copy of this sheet is enclosed.

Any additional filing fees required under 37 C.F.R. 1.16.

Any patent application processing fees under 37 CFR 1.17.

Signature

Dated: August 21, 2003

Philip W. Woo
Attorney of Record
Reg. No. 39,880

I certify that this document and fee is being deposited
on with the U.S. Postal Service as
first class mail under 37 C.F.R. 1.8 and is addressed to the
Assistant Commissioner for Patents, Washington, D.C.
20231.

Signature of Person Mailing Correspondence

Express Mail Label No.: EV 305 257 695 US

Typed or Printed Name of Person Mailing Correspondence

cc:



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RECEIVED
SEP -3 2003
TECHNOLOGY CENTER 2800

In re application of: Shibaek Nam, et al.
Title: Semiconductor Device Having Multi-Chip Package
Structure
Application No.: 10/038,714
Filing Date: January 2, 2002
Examiner: Pershelle L. Greene
Group Art Unit: 2826
Confirmation No.: 8922
Law Office: Sidley Austin Brown & Wood LLP
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This is a Response to the Office Action dated May 21, 2003 for the above-referenced Application. Applicants respectfully requests reconsideration of the Application in view of the following amendments and remarks.